

**Amendments to the Specification:**

Please amend the paragraph at p. 1, lns. 5-9, as follows:

This application is a continuation of Serial No. 09/961,355, filed September 25, 2001, the entire contents of which are incorporated herein by reference. This application is also based upon and claims the benefit of priority from the prior Japanese Patent Application No. 2000-301063, filed September 29, 2000, the entire contents of which are incorporated herein by reference.

Please delete the paragraph at p. 3, lns. 7-25.

Please delete the paragraph at p. 4, lns. 13-27.

Please amend the paragraph at p. 3, ln. 26 to p. 4, ln. 12, as follows:

A nonvolatile semiconductor memory ~~system~~package according to an ~~embodiment~~aspect of the present invention comprises: a memory device having a memory cell array including a plurality of nonvolatile semiconductor memory cells; a control portion configured to control the memory device; a network interface connectable to a network; a file management portion connected to the network interface configured to ~~manages~~manage a relationship between a data file given from the network and an address of the memory cell array; and a memory interface connected to the file management portion configured to convert a signal given from the network to a signal ~~which~~that is capable of being used at the control portion, wherein the package is wrapped by an insulating material.